

November 2020



AS7C256B

5V 32K X 8 CMOS SRAM (Common I/O)

Revision History

32K x 8 BIT HIGH SPEED CMOS SRAM

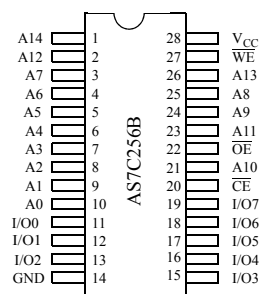
Revision	Details	Date
Rev 1.0	Initial Release	Sept. 2006
Rev 2.0	Delete EOL SOJ & TSOP part information	Nov. 2020

- Industrial (-40° to 85°C) temperature
- Organization: 32,768 words \times 8 bits
- High speed
 - 15ns address access time
 - 7ns output enable access time
- Low power consumption via chip deselect
- One chip select plus one Output Enable pin
- Bidirectional data inputs and outputs
- TTL-compatible

- 28-pin JEDEC standard packages
 - 300 mil PDIP
- ESD protection ≥ 2000 volts

The diagram illustrates the 32,768 X 8 Array architecture. It features a central array block labeled "32,768 X 8 Array (262,144)". To the left of the array is an "Address decoder" block that takes address inputs A0 through A7. Above the array is an "Input buffer" block. To the right of the array is a "Sense amp" block. Below the array is another "Address decoder" block that takes address inputs A8 through A14. To the right of the bottom address decoder is a "Control circuit" block with inputs \overline{WE} , \overline{OE} , and \overline{CE} . The array is connected to an "I/O" bus on the right, which has multiple data lines and control lines I/O0 and I/O7. Power supply inputs V_{CC} and GND are shown at the top left.

28-pin DIP (300 mil)





Functional description

The AS7C256B is a 5V high-performance CMOS 262,144-bit Static Random-Access Memory (SRAM) device organized as 32,768 words \times 8 bits. It is designed for memory applications requiring fast data access at low voltage, including Pentium™, PowerPC™, and portable computing. Alliance's advanced circuit design and process techniques permit 5.0V operation without sacrificing performance or operating margins.

The device enters *standby mode* when \overline{CE} is high. Equal address access and cycle times (t_{AA} , t_{RC} , t_{WC}) of 15 ns with output enable access times (t_{OE}) of 7ns are ideal for high-performance applications. The chip enable (\overline{CE}) input permits easy memory expansion with multiple-bank memory organizations.

A write cycle is accomplished by asserting chip enable (\overline{CE}) and write enable (\overline{WE}) LOW. Data on the input pins I/O0-I/O7 is written on the rising edge of \overline{WE} (write cycle 1) or \overline{CE} (write cycle 2). To avoid bus contention, external devices should drive I/O pins only after outputs have been disabled with output enable (\overline{OE}) or write enable (\overline{WE}).

A read cycle is accomplished by asserting chip enable (\overline{CE}) and output enable (\overline{OE}) LOW, with write enable (\overline{WE}) high. The chip drives I/O pins with the data word referenced by the input address. When chip enable or output enable is high, or write enable is low, output drivers stay in high-impedance mode.

All chip inputs and outputs are TTL-compatible. Operation is from a single 5.0 \pm 0.5V supply. The AS7C256B is packaged in high volume industry standard packages.

Absolute maximum ratings

Parameter	Symbol	Min	Max	Unit
Voltage on V_{CC} relative to GND	V_{t1}	-0.5	+7.0	V
Voltage on any pin relative to GND	V_{t2}	-0.5	$V_{CC} + 0.5$	V
Power dissipation	P_D	—	1.25	W
Storage temperature (plastic)	T_{stg}	-55	+125	°C
Ambient temperature with V_{CC} applied	T_{bias}	-55	+125	°C
DC current into outputs (low)	I_{OUT}	—	50	mA

Note:

Stresses greater than those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions outside those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Truth table

\overline{CE}	\overline{WE}	\overline{OE}	Data	Mode
H	X	X	High Z	Standby (I_{SB} , I_{SB1})
L	H	H	High Z	Output disable (I_{CC})
L	H	L	D_{OUT}	Read (I_{CC})
L	L	X	D_{IN}	Write (I_{CC})

Notes:

H = V_{IH} , L = V_{IL} , x = Don't care.

$V_{LC} = 0.2V$, $V_{HC} = V_{CC} - 0.2V$.

Other inputs $\geq V_{HC}$ or V_{LC} .



Recommended operating conditions

Parameter	Symbol	Min	Typical	Max	Unit
Supply voltage	V_{CC}	4.5	5.0	5.5	V
Input voltage	V_{IH}	2.2	–	$V_{CC}+0.5$	V
	$V_{IL}^{(1)}$	$-0.5^{(1)}$	–	0.8	V
Ambient operating temperature (Industrial)	T_A	–40	–	85	°C

Note:

1 V_{IL} min = –1.5V for pulse width less than 10ns, once per cycle.

DC operating characteristics (over the operating range)¹

Parameter	Symbol	Test conditions	AS7C256B-17		Unit
			Min	Max	
Input leakage current	$ I_{LI} $	$V_{CC} = \text{Max}, V_{in} = \text{GND to } V_{CC}$	–	5	μA
Output leakage current	$ I_{LO} $	$V_{CC} = \text{Max}, \overline{CS} = V_{IH}, V_{OUT} = \text{GND to } V_{CC}$	–	5	μA
Operating power supply current	I_{CC}	$V_{CC} = \text{Max}, \overline{CE} \leq V_{IL}, f = f_{Max}, I_{OUT} = 0\text{mA}$	–	150	mA
Standby power supply current	I_{SB}	$V_{CC} = \text{Max}, \overline{CE} \geq V_{IH}, f = f_{Max}, I_{OUT} = 0\text{mA}$	–	40	mA
	I_{SB1}	$V_{CC} = \text{Max}, \overline{CE} \geq V_{CC}-0.2\text{V}, V_{IN} \leq \text{GND} + 0.2\text{V or } V_{IN} \geq V_{CC}-0.2\text{V}, f = 0^{(2)}$	–	15	mA
Output voltage	V_{OL}	$I_{OL} = 8\text{ mA}, V_{CC} = \text{Min}$	–	0.4	V
	V_{OH}	$I_{OH} = -4\text{ mA}, V_{CC} = \text{Min}$	2.4	–	V

Notes:

All values are maximum guaranteed values.

$f_{Max} = 1/t_{RC}$, only address inputs cycling at f_{Max} , $f = 0$ means that no inputs are cycling.

Capacitance ($f = 1\text{MHz}$, $T_a = \text{room temperature}$, $V_{CC} = \text{NOMINAL}$)²

Parameter	Symbol	Signals	Test conditions	Max	Unit
Input capacitance	C_{IN}	A, \overline{CE} , \overline{WE} , \overline{OE}	$V_{in} = 0\text{V}$	7	pF
I/O capacitance	$C_{I/O}$	I/O	$V_{out} = 0\text{V}$	7	pF

Note:

This parameter is guaranteed by device characterization, but is not production tested.



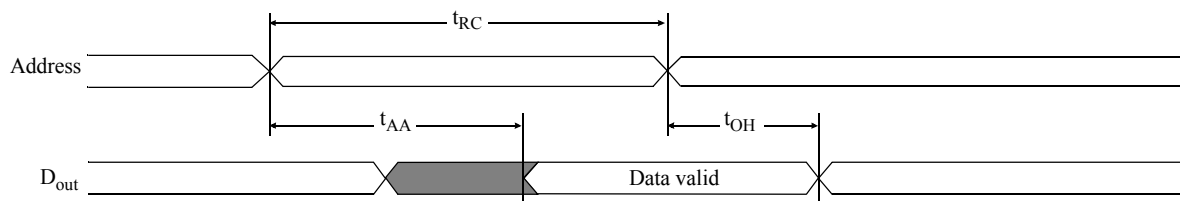
Read cycle (over the operating range)^{3,9}

Parameter	Symbol	AS7C256B-17		Unit	Notes
		Min	Max		
Read cycle time	t_{RC}	15	-	ns	
Address access time	t_{AA}		15	ns	3
Chip enable (\overline{CE}) access time	t_{ACE}		15	ns	3
Output enable (\overline{OE}) access time	t_{OE}	-	7	ns	
Output hold from address change	t_{OH}	3	-	ns	5
\overline{CE} LOW to output in low Z	t_{CLZ}	4	-	ns	4, 5
\overline{CE} HIGH to output in high Z	t_{CHZ}	0	7	ns	4, 5
\overline{OE} LOW to output in low Z	t_{OLZ}	0	-	ns	4, 5
\overline{OE} HIGH to output in high Z	t_{OHZ}	0	6	ns	4, 5
Power up time	t_{PU}	0	-	ns	4, 5
Power down time	t_{PD}	-	15	ns	4, 5

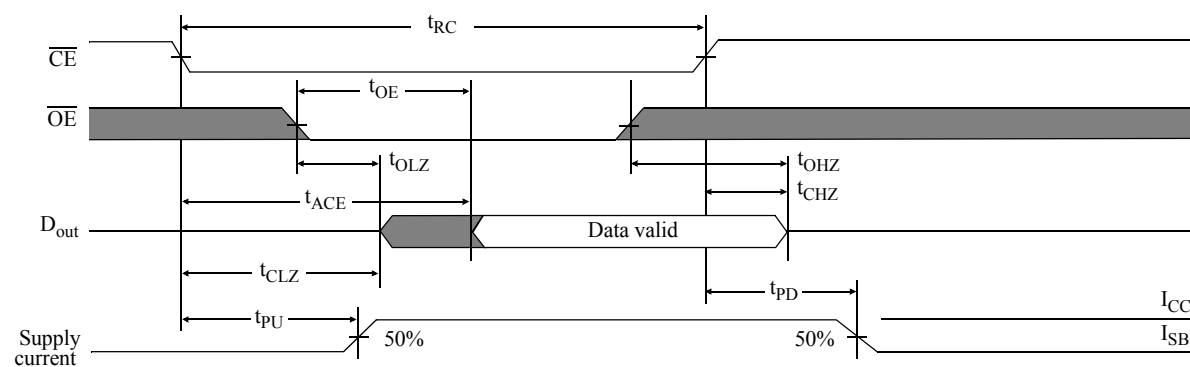
Key to switching waveforms

Rising input
 Falling input
 Undefined output/don't care

Read waveform 1 (address controlled)^{3,6,7,9}



Read waveform 2 (\overline{CE} controlled)^{3,6,8,9}



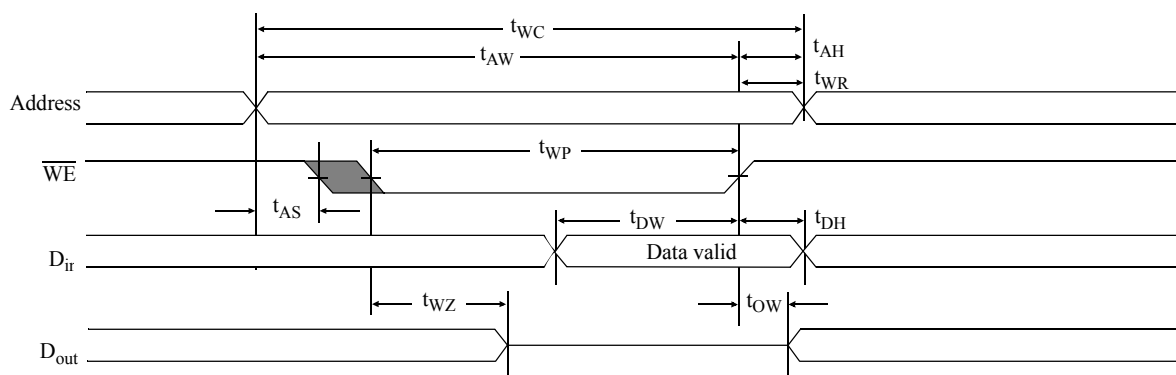


Write cycle (over the operating range)¹¹

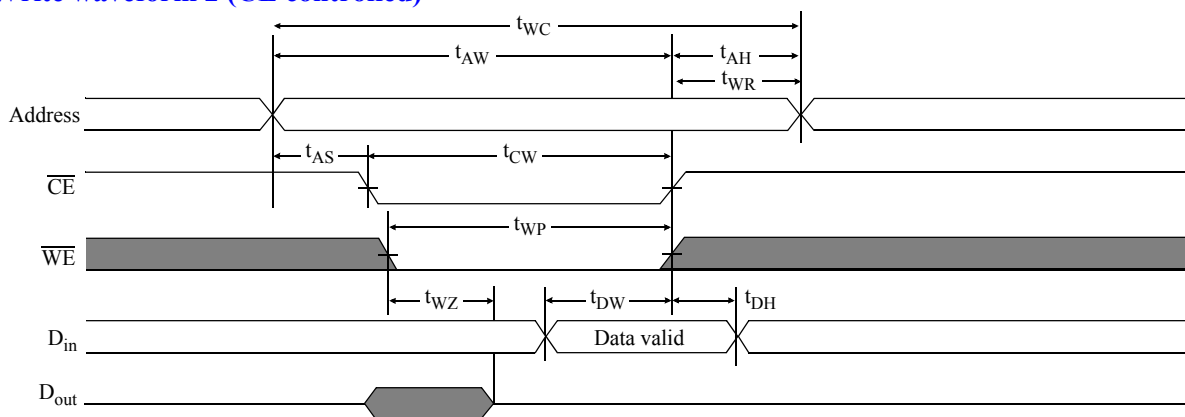
Parameter	Symbol	AS7C256B-15		Unit	Notes
		Min	Max		
Write cycle time	t_{WC}	15	–	ns	
Chip enable to write end	t_{CW}	10	–	ns	
Address setup to write end	t_{AW}	10	–	ns	
Address setup time	t_{AS}	0	–	ns	
Write pulse width	t_{WP}	10	–	ns	
Write recovery time	t_{WR}	0	–	ns	
Address hold from end of write	t_{AH}	0	–	ns	
Data valid to write end	t_{DW}	7	–	ns	
Data hold time	t_{DH}	0	–	ns	4, 5
Write enable to output in high Z	t_{WZ}	0	6	ns	4, 5
Output active from write end	t_{OW}	4	–	ns	4, 5

Shaded areas contain advance information.

Write waveform 1 (\overline{WE} controlled)^{10,11}



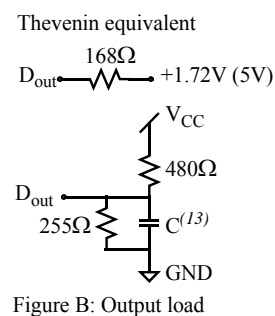
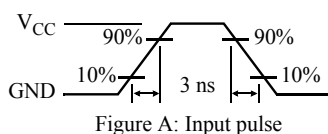
Write waveform 2 (\overline{CE} controlled)^{10,11}





AC test conditions

- Output load: see Figure B.
- Input pulse level: GND to V_{CC} . See Figure A.
- Input rise and fall times: 3 ns. See Figure A.
- Input and output timing reference levels: 1.5V.

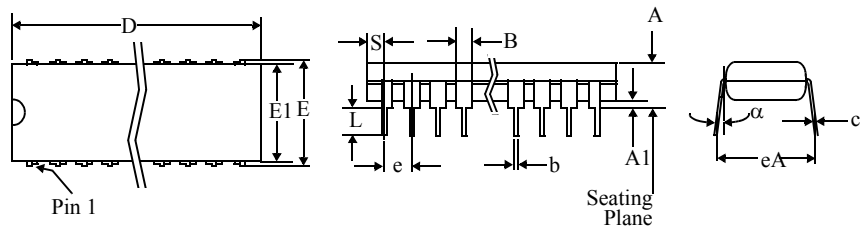


Notes

- 1 During V_{CC} power-up, a pull-up resistor to V_{CC} on \overline{CE} is required to meet I_{SB} specification.
- 2 This parameter is sampled, but not 100% tested.
- 3 For test conditions, see *AC Test Conditions*, Figures A and B.
- 4 These parameters are specified with $C_L = 5pF$, as in Figures B. Transition is measured $\pm 200mV$ from steady-state voltage.
- 5 This parameter is guaranteed, but not tested.
- 6 \overline{WE} is High for read cycle.
- 7 \overline{CE} and \overline{OE} are Low for read cycle.
- 8 Address valid prior to or coincident with \overline{CE} transition Low.
- 9 All read cycle timings are referenced from the last valid address to the first transitioning address.
- 10 \overline{CE} or \overline{WE} must be High during address transitions. Either \overline{CE} or \overline{WE} asserting high terminates a write cycle.
- 11 All write cycle timings are referenced from the last valid address to the first transitioning address.
- 12 $\overline{CE1}$ and $\overline{CE2}$ have identical timing.
- 13 $C = 30pF$, except on High Z and Low Z parameters, where $C = 5pF$.



Package diagrams



Note: This part is compatible with both pin numbering conventions used by various manufacturers.

28-pin PDIP		
	Min	Max
in mils		
A	-	0.180
A1	0.010	-
B	0.040	0.065
b	0.014	0.022
c	0.008	0.014
D	-	1.400
E	0.295	0.320
E1	0.278	0.298
e	0.100 BSC	
eA	0.330	0.380
L	0.120	0.140
a	0°	15°
S	-	0.055

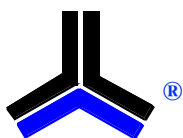


Ordering information

Package	Volt/Temp	15ns
Plastic DIP, 300 mil	5V industrial	AS7C256B-15PIN

Part numbering system

AS7C	256B	-15	P	I	N
SRAM prefix	Device number	Access time	Package: P=DIP 300 mil	Temperature range: I = -40C to 85C	N=Lead Free Part



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